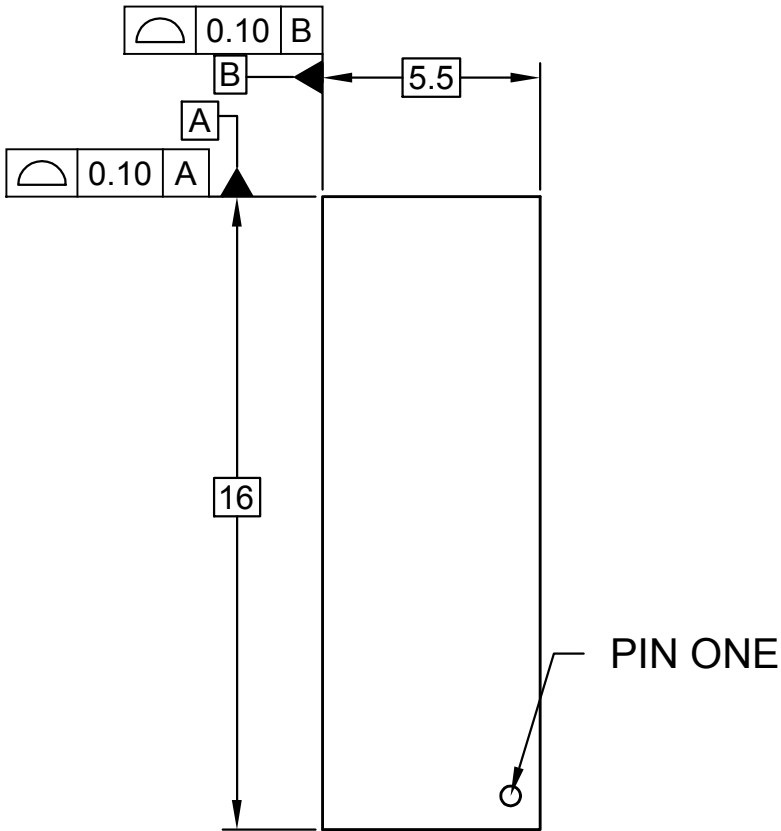
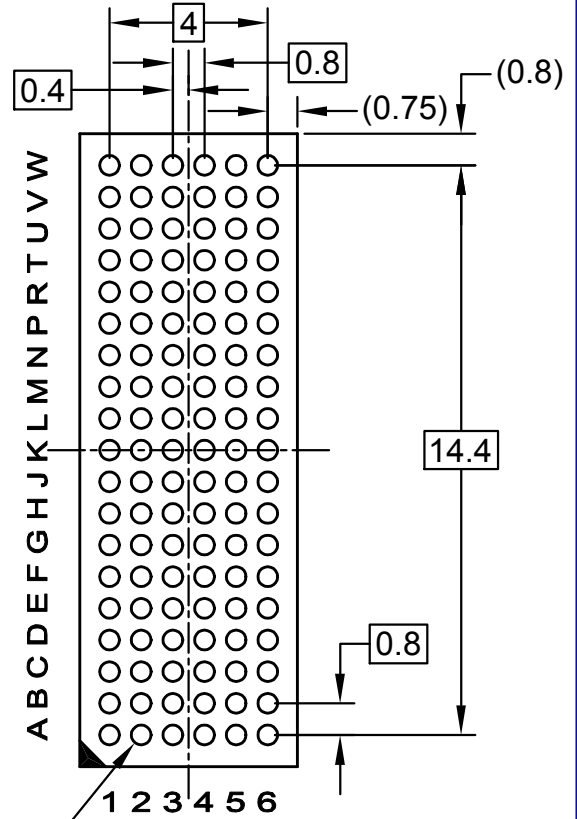


REVISIONS				
LTR	DESCRIPTION	EDCN	DATE	BY/APP'D
0	INITIAL DRAWING	NA	6-25-99	H.ALLEN
A	ADDED LANDPATTERN REC.	NA	1-26-00	H.Allen
B	CORRECTED THICKNESS DIM. RELEASED TO DOC CONTROL	NA	6-13-00	H.Allen
C	Added ball location tolerances	NA	8-24-00	J Kingsbury
D	Added Top and Bottom View Names Release to Document Control	ECN-MKT-BGA114revD	05-09-01	J Kingsbury
E	Changed Revision level only	ECN-MKT-BGA114ArevE	06-07-01	J Kingsbury



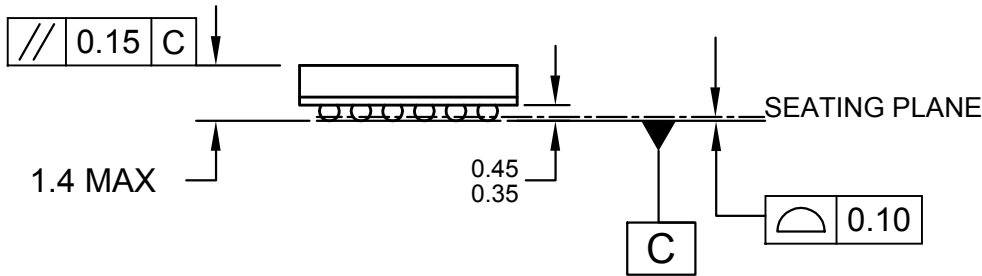
Top View



Bottom View

114X0.5<sup>+0.05</sup><sub>-0.05</sub>

⊕	0.15(M)	C	A	B
	0.08(M)	C		



NOTES:

- A. THIS PACKAGE CONFORMS TO JEDEC M0-205
- B. ALL DIMENSIONS IN MILLIMETERS
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)  
.35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
- D. DRAWING CONFORMS TO ASME Y14.5M-1994

BGA114ArevE

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR		
DRAWN H. Allen	6-25-99	333 Western Ave. S. Portland, Maine		
DFTG. CHK. J.Kingsbury	01-24-01	114BALL, FBGA, JEDEC M0-205, 5.5MM WIDE		
ENGR. CHK. J.Kingsbury	01-24-01	SCALE N/A	SIZE N/A	DRAWING NUMBER MKT-BGA114A
		DO NOT SCALE DRAWING		REV E
		SHEET 1 of 1		